

# APPROVAL SHEET

## MULTILAYER CERAMIC CAPACITORS

Capacitor Arrays Series (10V to 50V)

4 x 0402, 4 x 0603 Size

NP0, X7R & Y5V Dielectrics

**RoHS Compliance** 

\*Contents in this sheet are subject to change without prior notice.



## 1. INTRODUCTION

WTC middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

WTC capacitor arrays are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

## 2. FEATURES

- a. High density mounting due to mounting space saving.
- b. Mounting cost saving.
- c. Increased throughput.

## 3. APPLICATIONS

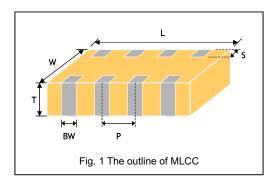
- For use as a bypass for digital and analog signal line noise
- b. Computer motherboards and peripherals.
- c. The other common electronic circuits.

## **4. HOW TO ORDER**

<u>Y</u>	<u>4C</u>	<u>3</u>	<u>B</u>	<u>103</u>	<u>K</u>	<u>500</u>	<u>C</u>	Ī
<u>Series</u>	Cap. Nr.	Termination pitch	Dielectric	Capacitance	<u>Tolerance</u>	Rated voltage	Termination	<u>Packaging</u>
<b>Y</b> =Capacitor	<b>4C</b> =4xCap	<b>3</b> =0.03" pitch	<b>N</b> =NP0	Two significant	<b>J</b> =±5%	Two significant	<b>C</b> =Cu/Ni/Sn	T=7" reeled
array	·	<b>2</b> =0.02" pitch	(C0G)	digits followed	<b>K</b> =±10%	digits followed		
			<b>B</b> =X7R	by no. of zeros.	M=±20%	by no. of zeros.		
			F=Y5V	And R is in	<b>Z</b> =-20/+80%	And R is in		
				place of		place of decimal		
				decimal point.		point.		
				eg.:		eg.:		
				103=10x10 <sup>3</sup>		<b>100</b> =10 VDC		
				=10,000pF		<b>160</b> =16 VDC		
				=10nF		<b>250</b> =25 VDC		
						<b>500</b> =50 VDC		



## **5. EXTERNAL DIMENSIONS**



Size Inch (mm)	L (mm)	W (mm)	T (mm)/Sym	bol	S (mm)	BW (mm)	P (mm)
0508 (1220)	2.00±0.15	1.25±0.15	0.85±0.10	Т	0.20±0.10	0.25±0.10	0.50±0.10
0612 (1632)	3.20±0.15	1.60±0.15	0.80±0.10	В	0.30±0.20	0.40±0.15	0.80±0.15

Reflow soldering process only.

## **6. GENERAL ELECTRICAL DATA**

Dielectric	Ni	>0	X7	Y5V	
Size	4x0402 4x0603		4x0402	4x0603	4x0603
Capacitance*	10pF to 270pF	10pF to 470pF	1000pF to 100nF	180pF to 100nF	10nF to 100nF
Capacitance tolerance**	<b>ce**</b> J (±5%), K (±10%)		K (±10%),	K (±10%), M (±20%)	
Rated voltage (WVDC)	50V 25, 50V 1		10V, 16V, 25V, 50V	16V, 25V, 50V	16V, 50V
Q/Tan δ*	Cap<30pF: Q≥400+20C Cap≥30pF: Q≥1000		Ur=50V, ≤2.5% Ur=25V&16V, ≤3.5% Ur=10V, ≤5.0%		Ur=50V, ≤5% Ur=16V, ≤7%
Insulation resistance at Ur	≥10	GΩ	≥10GΩ or RxC≥500ΩxF whichever is less		
Operating temperature		-55 to	+125℃	-25 to +85℃	
Capacitance characteristic	±30ppm		±15%		+30/-80%
Termination			Ni/Sn (lead-free termination)		

<sup>\*</sup> Measured at 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the conditions of 25℃ ambient temperature.

X7R: Apply 1.0 $\pm$ 0.2Vrms, 1.0kHz $\pm$ 10%, at the conditions of 25°C ambient temperature.

Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 20℃ ambient temperature.

<sup>\*\*</sup> Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.



## 7. CAPACITANCE RANGE

SIZE				4 x 0402			4 x 0603						
DIELECTRIC		NP0	X7R		NP0			X7R		Y5V			
R/	TED VOLTAGE (VDC)	50	10	16	25	50	25	50	16	25	50	16	50
	10pF (100)	Т					В	В					
	15pF (150)	Т					В	В					
	22pF (220)						В	В					
	33pF (330)	Т					В	В					
	47pF (470)	Т					В	В					
	68pF (680)	Т					В	В					
	100pF (101)	T					В	В					
	150pF (151)	Т					В	В					
	180pF (181)	Т					В	В		В	В		
	220pF (221)	Т					В	В		В	В		
	270pF (271)						В	В		В	В		
ą.	330pF (331)						В	В		В	В		
anc	470pF (471)						В	В		В	В		
acit	6,80pF (681)									В	В		
Capacitance	1,000pF (102)		Т	Т	Т	Т				В	В		
0	1,500pF (152)		Т	Т	Т	Т				В	В		
	2,200pF (222)		Т	Т	Т	Т				В	В		
	3,300pF (332)		Т	Т	Т	Т				В	В		
	4,700pF (472)		Т	Т	Т	Т				В	В		
	6,800pF (682)		Т	Т	Т	Т				В	В		
	0.010µF (103)		Т	Т	Т	Т				В	В		В
	0.015µF (153)		Т	Т	Т		ļ		В	В	В		В
	0.022µF (223)		Т	Т	Т		ļ		В	В	В		В
	0.033µF (333)		Т	Т	Т		ļ		В				В
	0.047µF (473)		Т	Т	Т				В				В
	0.068µF (683)		Т	Т	Т				В				В
	0.10µF (104)		Т	Т	Т				В			В	В

<sup>1.</sup> The letter in cell is expressed the symbol of product thickness.

## **8. PACKAGING DIMENSION AND QUANTITY**

Size	Thickness/Syn	nbol	Paper tape		
Size	(mm)		7" reel	13" reel	
4 x 0402	0.85±0.10	Т	4k	-	
4 x 0603	0.80±0.10	В	4k	-	

Unit: pieces



## 9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

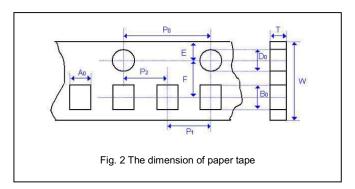
No.	Item	Test Condition	Requirements		
1.	Visual and		* No remarkable defect.		
	Mechanical		* Dimensions to conform to individual specification sheet.		
2.	Capacitance	Class I: (NP0)	* Shall not exceed the limits given in the detailed spec.		
3.	Q/ D.F.	1.0±0.2Vrms, 1MHz±10%	NP0: Cap≥30pF, Q≥1000; Cap<30pF, Q≥400+20C		
	(Dissipation	Class II: (X7R, Y5V)	X7R: Ur=50V, ≤2.5%; Ur=25V&16V, ≤3.5%; Ur=10V, ≤5.0%		
	Factor)	1.0±0.2Vrms, 1kHz±10%	Y5V: Ur=50V, ≤5%; Ur=16V, ≤7%		
4.	Dielectric	* To apply 250% rated voltage.	* No evidence of damage or flash over during test.		
	Strength	* Duration: 1 to 5 sec.			
		* Charge and discharge current less than 50mA.			
5.	Insulation	To apply rated voltage for max. 120 sec.	≥10GΩ or RxC≥500Ω-F whichever is smaller.		
	Resistance				
6.	Temperature	With no electrical load.			
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change		
		NP0 -55~125℃ at 25℃	NP0 Within ±30ppm/℃		
		X7R	X7R Within ±15% Y5V Within +30%/-80%		
		Y5V  -25~85℃ at 20℃	Y5V Within +30%/-80%		
7.	Adhesive	* Pressurizing force :	* No remarkable damage or removal of the terminations.		
	Strength of	5N (≤0603) and 10N (>0603)			
	Termination	* Test time: 10±1 sec.			
8.	Vibration	* Vibration frequency: 10~55 Hz/min.	* No remarkable damage.		
	Resistance	* Total amplitude: 1.5mm	* Cap change and Q/D.F.: To meet initial spec.		
		* Test time: 6 hrs. (Two hrs each in three mutually			
		perpendicular directions.)			
		* Measurement to be made after keeping at room temp. for			
		24±2 hrs.			
9.	Solderability	* Solder temperature: 235±5℃	95% min. coverage of all metalized area.		
40		** Dipping time: 2±0.5 sec.			
10.	Bending Test				
		of the pressurizing rod at a rate of about 1 mm per second until			
		the deflection becomes 1 mm and then the pressure shall be maintained for 5±1 sec.	NP0: within ±5.0% or ±0.5pF whichever is larger.  X7R: within ±12.5%		
		** Measurement to be made after keeping at room temp. for	Y5V: within ±30%		
		24±2 hrs.	(This capacitance change means the change of capacitance under		
			specified flexure of substrate from the capacitance measured before		
			the test.)		
11.	Resistance to	* Solder temperature: 260±5℃	* No remarkable damage.		
		* Dipping time: 10±1 sec	* Cap change:		
		* Preheating: 120 to 150℃ for 1 minute before imme rse the	NP0: within ±2.5% or ±0.25pF whichever is larger.		
		capacitor in a eutectic solder.	X7R: within ±7.5%		
		* Before initial measurement (Class II only): Perform	Y5V: within ±20%		
		150+0/-10℃ for 1 hr and then set for 24±2 hrs at r oom temp.	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.		
		* Measurement to be made after keeping at room temp. for	* 25% max. leaching on each edge.		
		24±2 hrs.			

No.	Item		Test Condition		Requirements
12.	Temperature		t the five cycles according to the temper	eratures and	No remarkable damage.
	Cycle	time.	T (%)	Fire a (main )	Cap change:
		Step 1		Time (min.) 0±3	NP0: within ±2.5% or ±0.25pF whichever is larger.
		2	Room temp. 2~		X7R: within ±7.5%
		3	· · ·	)±3	Y5V: within ±20%
		4	Room temp. 2~		* Q/D.F., I.R. and dielectric strength: To meet initial requirements.
		* Before i	nitial measurement (Class II only): Per	rform	
		1	0℃ for 1 hr and then set for 24±2 hrs a		
			ement to be made after keeping at roor	•	
		24±2 hrs.		,	
13.	Humidity	* Test ten	np.: 40±2℃		
	(Damp Heat)	* Humidit	y: 90~95% RH		* No remarkable damage.
	Steady State	* Test tim	e: 500+24/-0hrs.		* Cap change: NP0: within ±5.0% or ±0.5pF whichever is larger.
		*Before in	nitial measurement (Class II only): Perf	form	X7R: within ±12.5%
		150+0/-1	0 $℃$ for 1 hr and then set for 24±2 hrs a	at room temp.	Y5V: within ±30%
		* Measur	ement to be made after keeping at roor	m temp. for	* Q/D.F. value:
		24±2 hrs			NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C
					Cap<10pF; Q≥200+10C
					X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5%
					Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%
					* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.
14.	Humidity	* Test ten	np.: 40±2℃		* No remarkable damage.
	(Damp Heat)	* Humidit	y: 90~95%RH		* Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger.
	Load	* Test tim	e: 500+24/-0 hrs.		X7R: within ±12.5%
		* To apply	voltage: rated voltage.		Y5V: within ±30%
		* Before i	nitial measurement (Class II only): To a	apply test	* Q/D.F. value:
		voltage fo	or 1hr at 40℃ and then set for 24±2 hrs	at room temp.	NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C
		* Measur	ement to be made after keeping at room	m temp. for	X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5%
		24±2 hrs	3.		Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%
					* I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.
15.	High	* Test ten	np.:		* No remarkable damage.
	Temperature	NP0, X	7R: 125±3℃		* Cap change: NP0: within ±3.0% or ±0.3pF whichever is larger.
	Load	Y5V: 85	5±3℃		X7R: within ±12.5%
	(Endurance)	* To apply	voltage: 200% of rated voltage.		Y5V: within ±30%
		* Test tim	e: 1000+24/-0 hrs.		* Q/D.F. value:
		*Before in	nitial measurement (Class II only): To a	apply test	NP0: Cap≥30pF, Q≥350
		voltage fo	or 1hr at test temp. and then set for 24±	±2 hrs at room	10pF≤Cap<30pF, Q≥275+2.5C
		temp.			Cap<10pF, Q≥200+10C
		*Measure	ement to be made after keeping at roon	n temp. for	X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5%
		24±2 hrs			Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%
					* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.

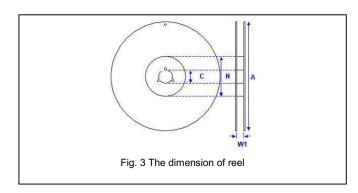


## **APPENDIXES**

## **■ Tape & reel dimensions**

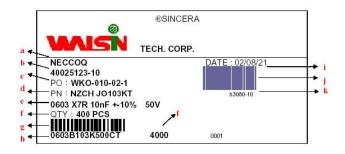


Size	4x0402	4x0603
Thickness	T	В
$A_0$	1.50±0.10	2.00±0.10
B <sub>0</sub>	2.30±0.10	3.50±0.10
Т	0.95±0.05	0.95±0.05
K <sub>0</sub>	-	ı
w	8.00±0.10	8.00±0.10
P <sub>0</sub>	4.00±0.10	4.00±0.10
10xP₀	40.0±0.10	40.0±0.10
P <sub>1</sub>	4.00±0.10	4.00±0.10
P <sub>2</sub>	2.00±0.05	2.00±0.05
$D_0$	1.55±0.05	1.50±0.05
$D_1$	-	ı
E	1.75±0.05	1.75±0.10
F	3.50±0.05	3.50±0.05



Size	4x0402, 4x0603
Reel size	7"
С	13.0+0.5/-0.2
<b>W</b> <sub>1</sub>	8.4+1.5/-0
Α	178.0±0.10
N	60.0+1/-0

## Description of customer label

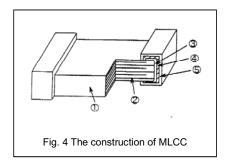


- a. Customer name
- b. WTC order series and item number
- c. Customer P/O
- d. Customer P/N
- e. Description of product
- f. Quantity
- g. Bar code including quantity & WTC P/N or customer
- h. WTC P/N
- i. Shipping date
- j. Order bar code including series and item numbers
- k. Serial number of label



#### Constructions

No.	Nan	пе	NP0, X7R, Y5V
0	Ceramic r	material	BaTiO₃ based
2	Inner ele	ctrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
(5)		Outer layer	Sn (Matt)



#### **■** Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

#### Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability.
   Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

#### Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of  $N_2$  within oven are recommended.

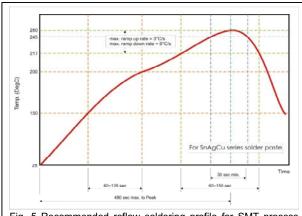


Fig. 5 Recommended reflow soldering profile for SMT process with SnAgCu series solder paste.

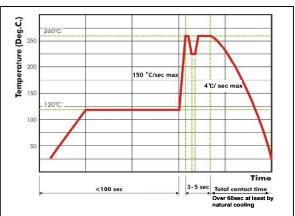


Fig. 6 Recommended wave soldering profile for SMT process with SnAgCu series solder.

## 单击下面可查看定价,库存,交付和生命周期等信息

>>Walsin Technology(华新科技)